

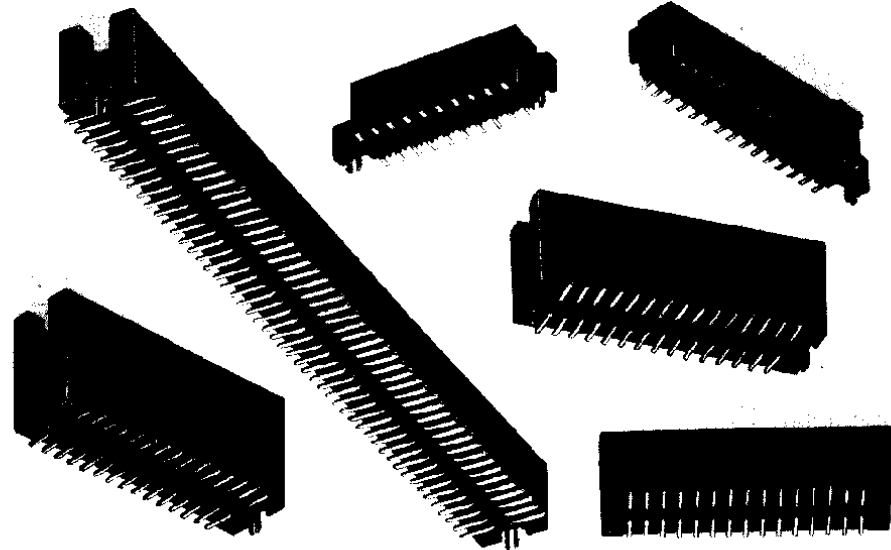


AMPMODU 50/50 Grid Connectors

Photo 91589

Product Facts

- Surface-mount products for parallel board-to-board applications, as well as right-angle board-to-board and cable-to-board applications (see page 61.)
- High density 1.27 x 1.27 [.050 x .050] centerline grid
- Three board-to-board stack heights: 6.35 [.250], 8.13 [.320] and 9.91 [.390]
- Non-protrusive metallic holddowns
- Reliable dual beam receptacle contacts for redundant contact
- Duplex plated receptacle and post contacts; gold plated on mating areas, tin-lead plated on tails
- Receptacle and header allow for drainage of processing fluids
- Polarized header and receptacle assemblies.
- Sizes of 10, 20, 30, 40, 50, 60, 70, 80 and 100 positions
- Available packaged on "tape-and-reel" for automatic placement per EIA standards
- Recognized under the Component Program of Underwriters Laboratories Inc., File No. E28476
- Certified by Canadian Standards Association File No. LR7189



AMPMODU 50/50 Grid vertical headers and receptacles are designed for parallel board-to-board stacking in high density applications.

Available are double row, vertical shrouded headers and receptacles in sizes ranging from 10 through 100 positions.

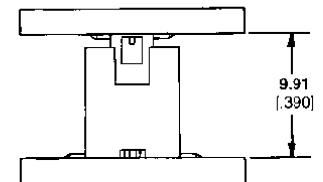
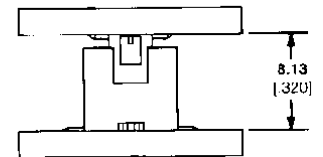
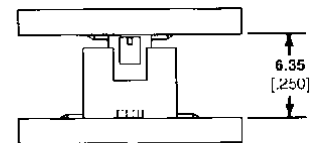
Parallel board-to-board stacking heights of 6.35 [.250], 8.13 [.320] and 9.91 [.390] are achievable by selection of the appropriate header. The receptacle is common for all three stacking heights.

Non-protrusive metallic holddowns are designed for use in 1.57 [.062], or thicker PC boards and allow surface mounting to both sides of the board. In addition to providing retention during processing, the holddowns are soldered during reflow and therefore provide long term strain relief for the lead solder joints.

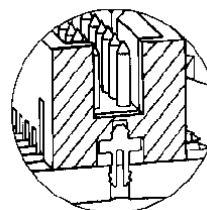
AMPMODU 50/50 Grid vertical headers and receptacles are compatible with standard surface-mount processes; IR (infrared) and VPR (vapor phase reflow). The surface-mount connectors have been designed so that dimensioning, tolerances, referenced datums, holddown characteristics and packaging methods result in a system that is compatible with robotic assembly.

The headers and receptacles feature polarization to prevent misalignment.

Board Stacking Heights



Non-Protrusive Metallic Holddowns



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